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(12) **United States Design Patent**  
**Lin**

(10) **Patent No.:** **US D494,169 S**

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(54) **COMPUTER HOUSING**

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Taiwan Hsien (TW)**

(\*\*) **Term:** **14 Years**

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(51) **LOC (7) Cl.** ..... **14-02**

(52) **U.S. Cl.** ..... **D14/349**

(58) **Field of Search** ..... D14/349, 353,  
D14/354, 356; D13/162, 184, 199; 312/223.1-223.3;  
360/99.01-99.12; 361/680-686, 690-696;  
369/34.01, 36.01

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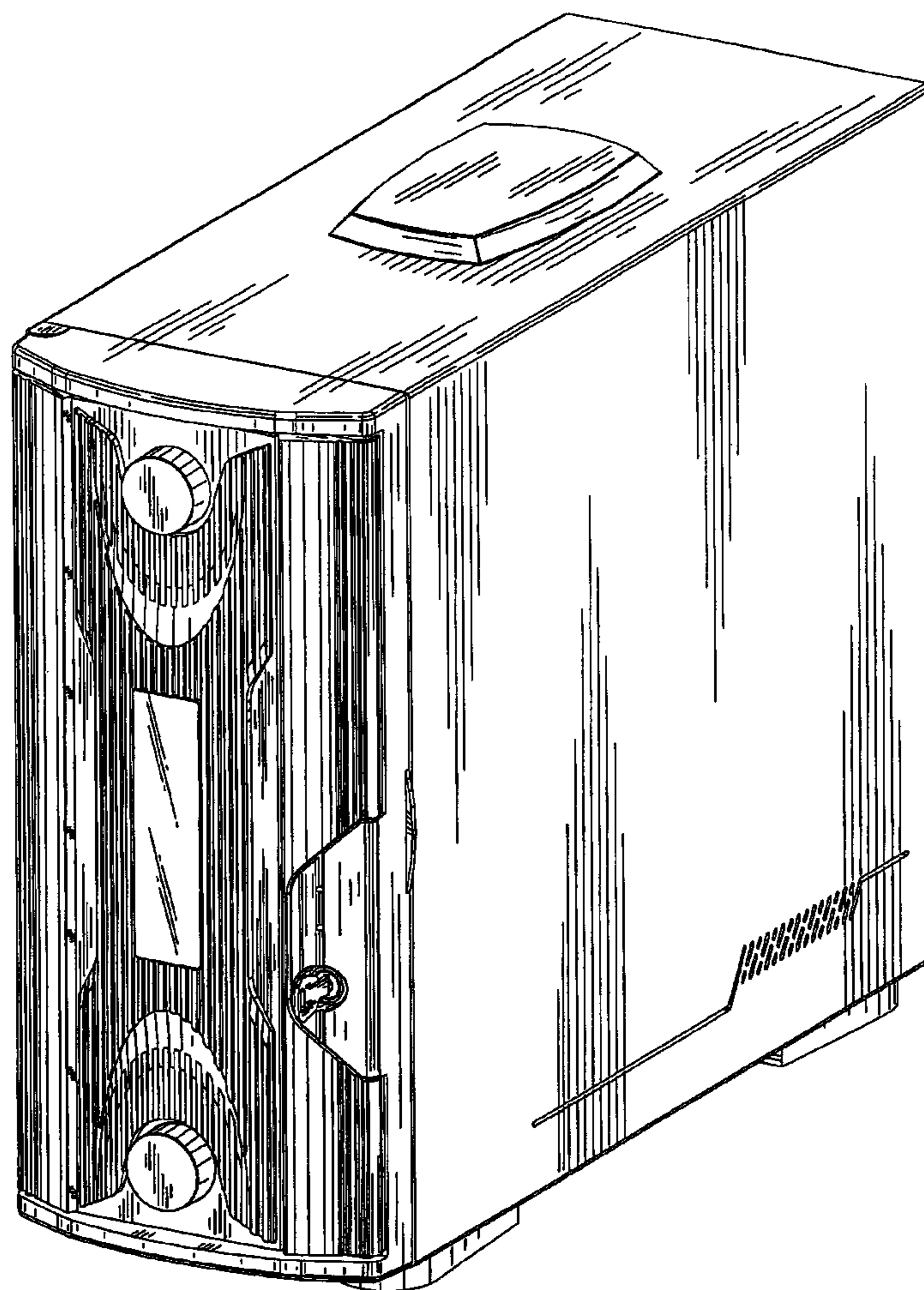
(57) **CLAIM**

The ornamental design for a computer housing, as shown and described.

**DESCRIPTION**

FIG. 1 is a top, front and right side perspective view of a computer housing showing my new design; FIG. 2 is a front elevational view thereof; FIG. 3 is a rear elevational view thereof; FIG. 4 is a left side elevational view thereof; FIG. 5 is a right elevational view thereof; FIG. 6 is a top plan view thereof; FIG. 7 is bottom plan view thereof; and, FIG. 8 is a top, front and left side perspective view thereof.

**1 Claim, 8 Drawing Sheets**



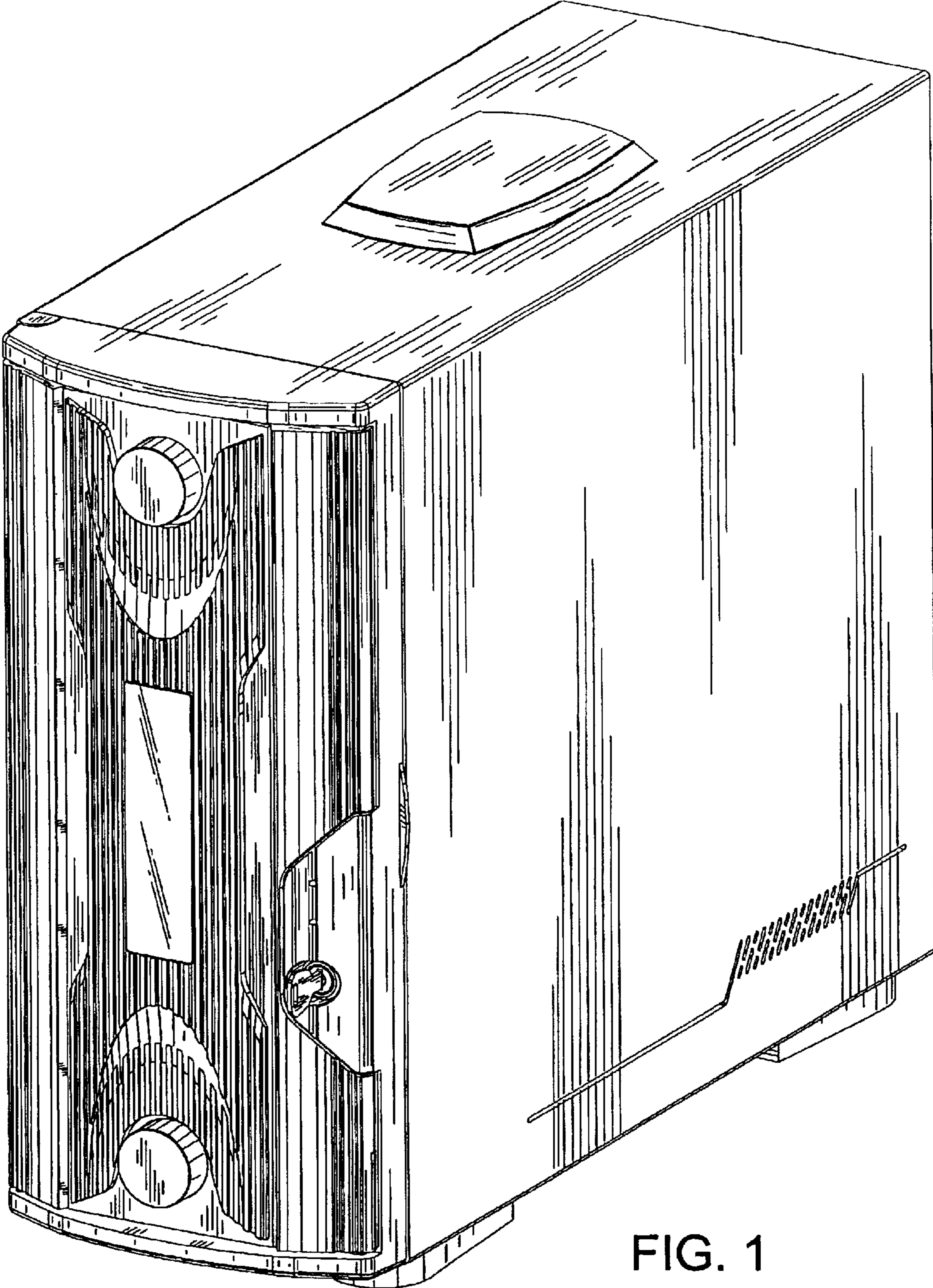


FIG. 1

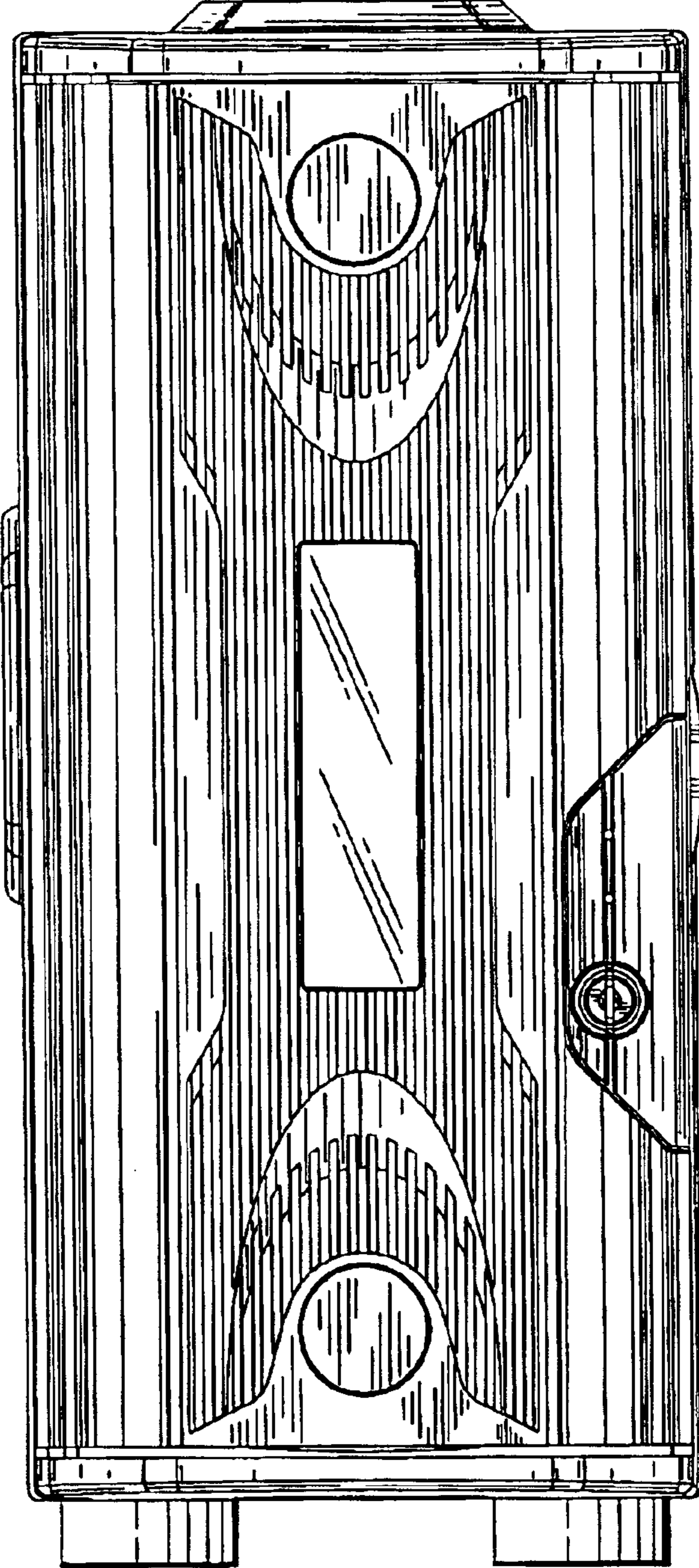


FIG. 2

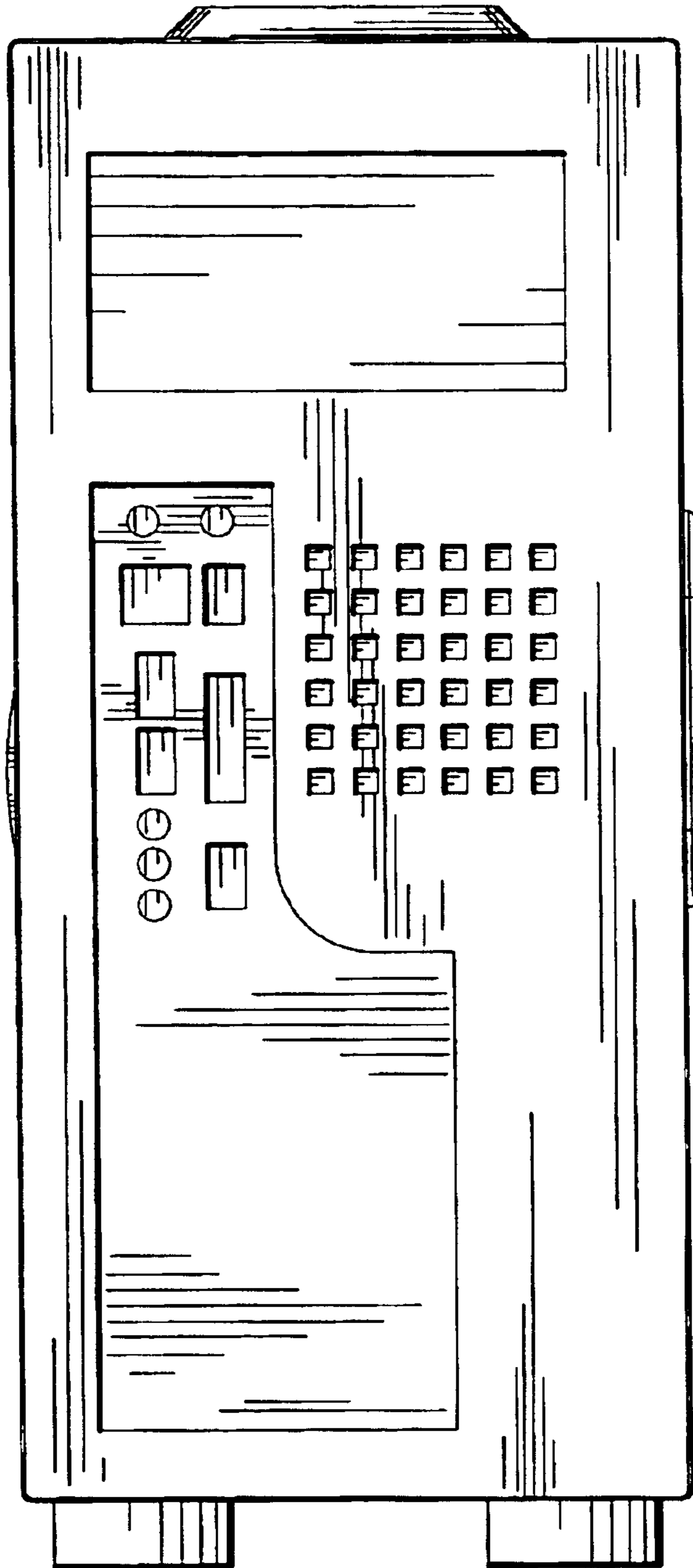


FIG. 3

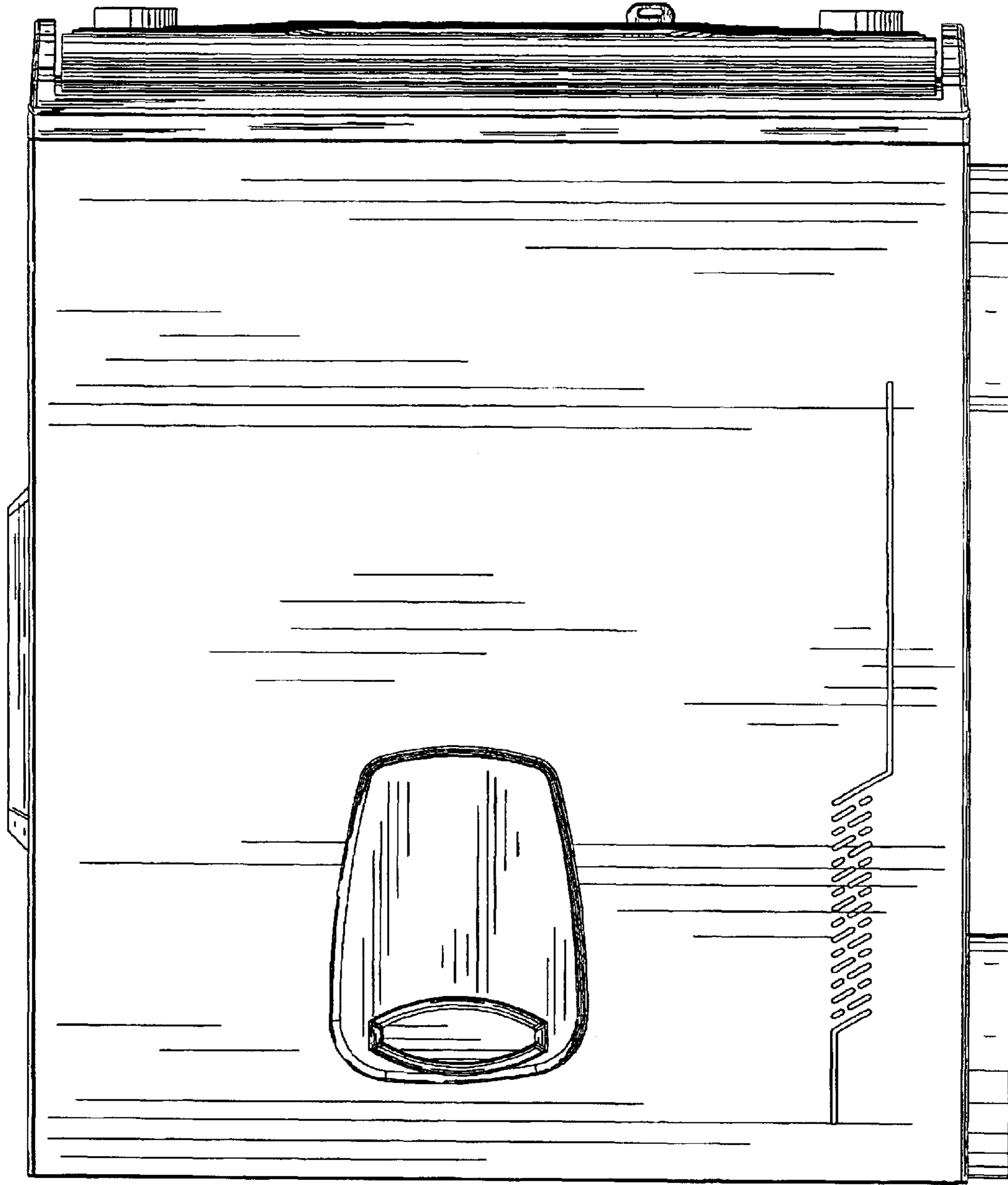


FIG. 4

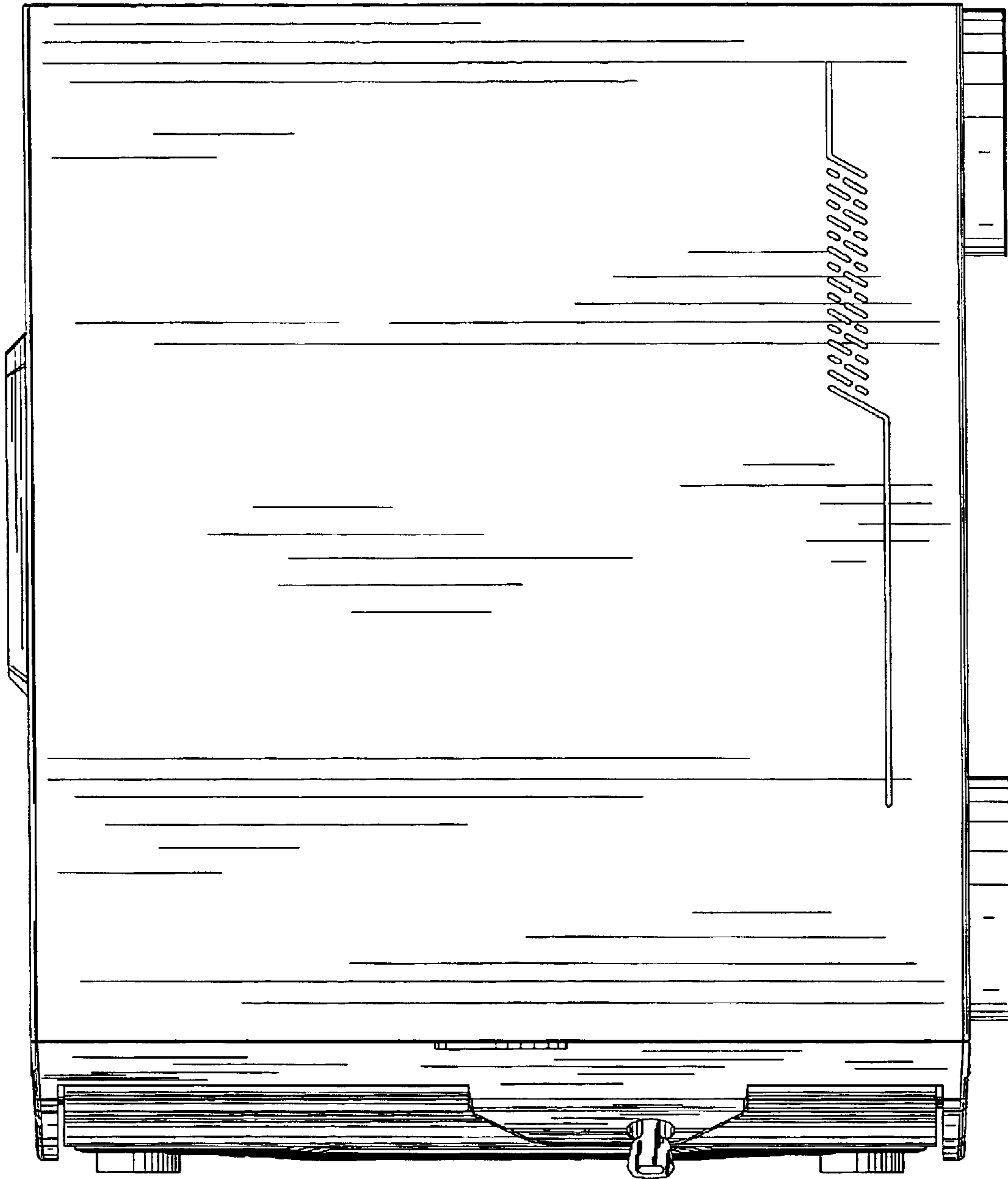


FIG. 5

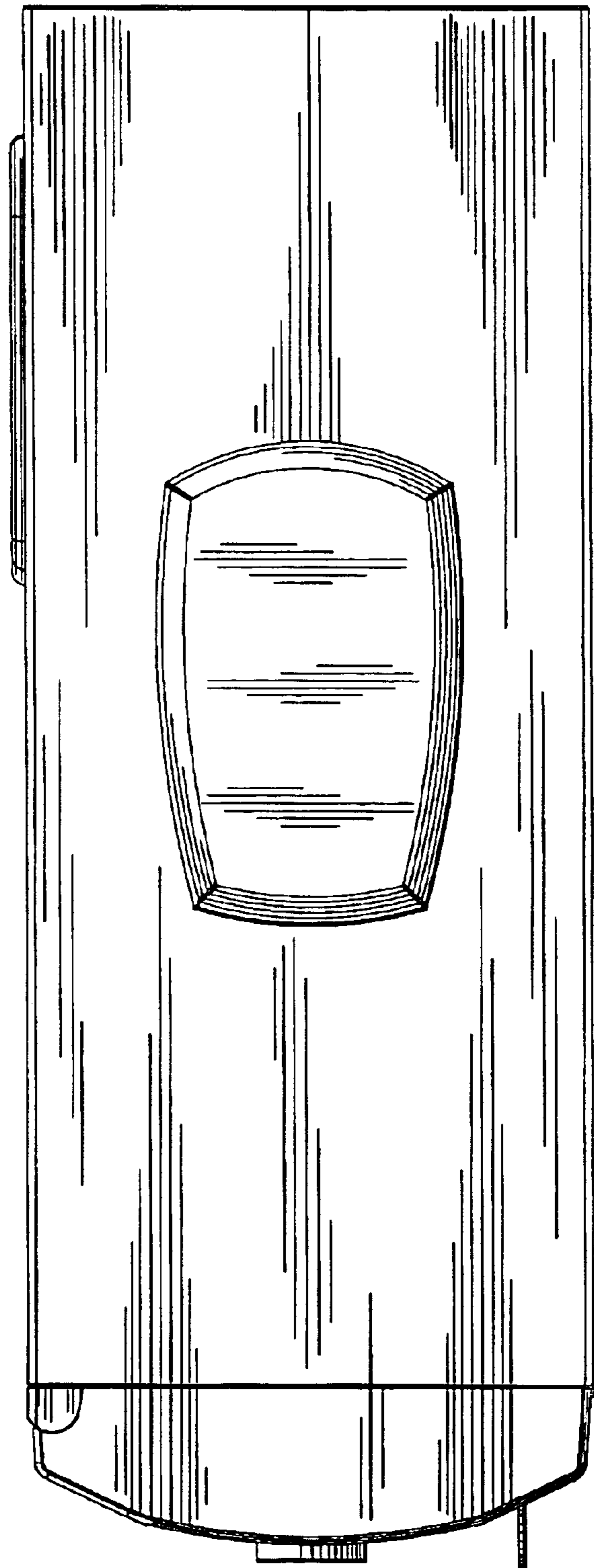


FIG. 6

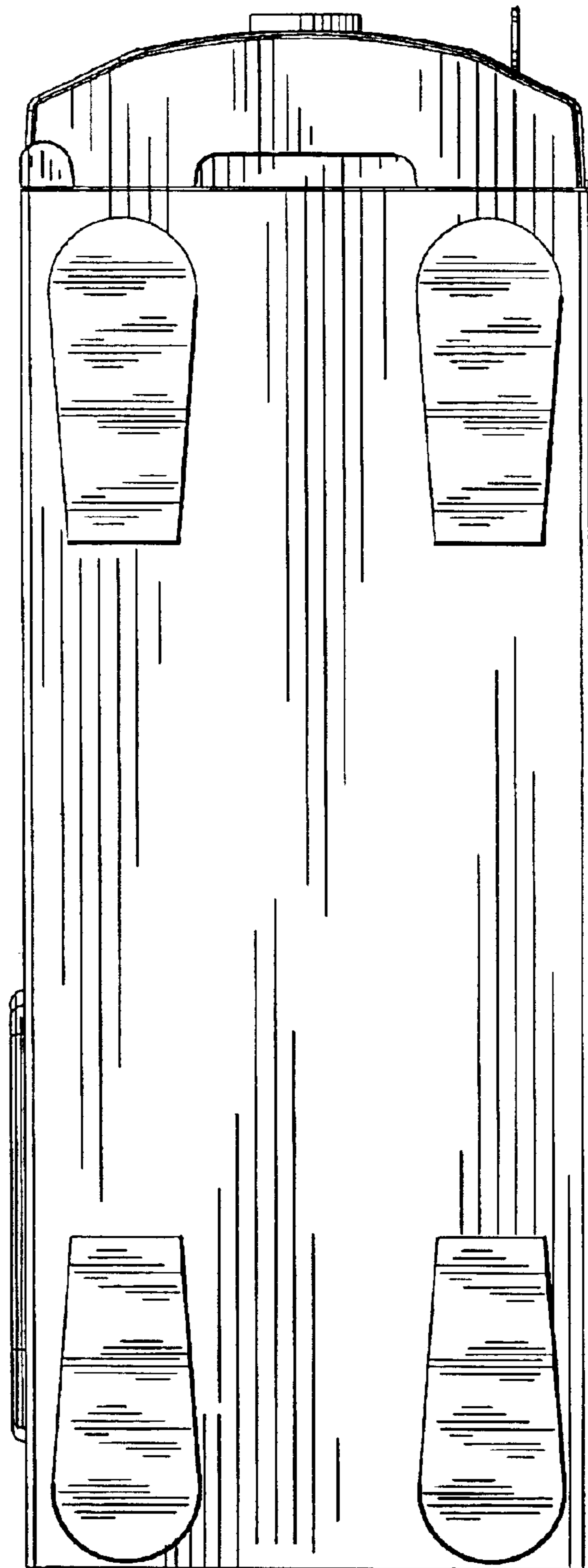


FIG. 7



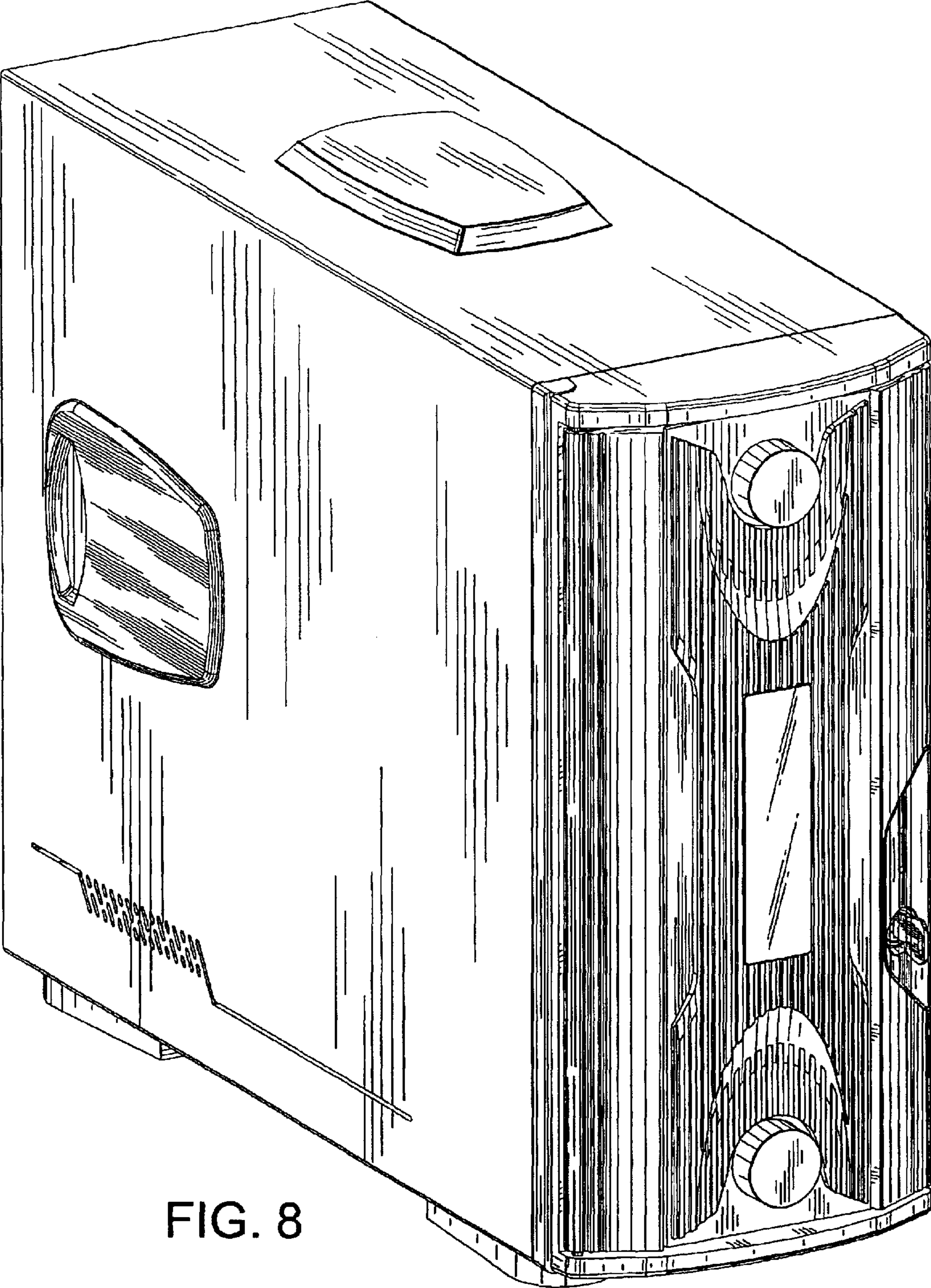


FIG. 8